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May 2014

## **FDMA8878**

# Single N-Channel Power Trench<sup>®</sup> MOSFET 30 V, 9.0 A, 16 m $\Omega$

#### **Features**

- Max  $r_{DS(on)} = 16 \text{ m}\Omega$  at  $V_{GS} = 10 \text{ V}$ ,  $I_D = 9.0 \text{ A}$
- Max  $r_{DS(on)}$  = 19 m $\Omega$  at  $V_{GS}$  = 4.5 V,  $I_D$  = 8.5 A
- High performance trench technology for extremely low r<sub>DS(on)</sub>
- Fast switching speed
- RoHS Compliant

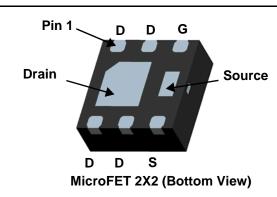
#### **General Description**

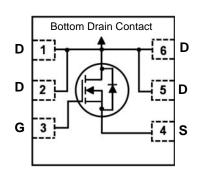
This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been optimized for  $r_{DS(on)}$ , switching performance.

#### **Application**

- DC/DC Buck Converters
- Load Switch in NB
- Notebook Battery Power Management







## MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

| Symbol                            | Parameter                                    |                        |           | Ratings     | Units |
|-----------------------------------|--|------------------------|-----------|-------------|-------|
| V <sub>DS</sub>                   | Drain to Source Voltage                      |                        |           | 30          | V     |
| $V_{GS}$                          | Gate to Source Voltage                       |                        | (Note 3)  | ±20         | V     |
|                                   | Drain Current -Continuous (Package Limited)  | T <sub>C</sub> = 25 °C |           | 10          |       |
| I <sub>D</sub>                    | -Continuous                                  | T <sub>A</sub> = 25 °C | (Note 1a) | 9.0         | Α     |
|                                   | -Pulsed                                      |                        |           | 40          |       |
| Б                                 | Power Dissipation                            | T <sub>A</sub> = 25 °C | (Note 1a) | 2.4         | W     |
| $P_{D}$                           | Power Dissipation                            | T <sub>A</sub> = 25 °C | (Note 1b) | 0.9         | VV    |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Junction Temperature R | ange                   |           | -55 to +150 | °C    |

#### **Thermal Characteristics**

| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | (Note 1a) | 52  | °C/W |
|-----------------|---|-----------|-----|------|
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | (Note 1b) | 145 | C/VV |

#### **Package Marking and Ordering Information**

| Device Marking | Device   | Package      | Reel Size | Tape Width | Quantity   |
|----------------|----------|--------------|-----------|------------|------------|
| 878            | FDMA8878 | MicroFET 2x2 | 7 "       | 8 mm       | 3000 units |

## Electrical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

| Symbol                               | Parameter                                 | Test Conditions                               | Min | Тур | Max | Units |
|--------------------------------------|---|---|-----|-----|-----|-------|
| Off Chara                            | cteristics                                |   |     |     |     |       |
| BV <sub>DSS</sub>                    | Drain to Source Breakdown Voltage         | $I_D = 250 \mu A, V_{GS} = 0 V$               | 30  |     |     | V     |
| $\Delta BV_{DSS} \over \Delta T_{J}$ | Breakdown Voltage Temperature Coefficient | I <sub>D</sub> = 250 μA, referenced to 25 °C  |     | 26  |     | mV/°C |
| I <sub>DSS</sub>                     | Zero Gate Voltage Drain Current           | V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V |     |     | 1   | μΑ    |
| I <sub>GSS</sub>                     | Gate to Source Leakage Current, Forward   | V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V |     |     | 100 | nA    |

#### **On Characteristics**

| $V_{GS(th)}$                     | Gate to Source Threshold Voltage                         | $V_{GS} = V_{DS}, I_D = 250 \mu A$                                       | 1.2 | 1.8 | 3.0 | V     |
|----------------------------------|--|--|-----|-----|-----|-------|
| $\Delta V_{GS(th)}$ $\Delta T_J$ | Gate to Source Threshold Voltage Temperature Coefficient | $I_D = 250 \mu A$ , referenced to 25 °C                                  |     | -5  |     | mV/°C |
| r <sub>DS(on)</sub>              |  | $V_{GS} = 10 \text{ V}, I_D = 9.0 \text{ A}$                             |     | 13  | 16  |       |
|                                  | Static Drain to Source On Resistance                     | $V_{GS} = 4.5 \text{ V}, I_D = 8.5 \text{ A}$                            |     | 16  | 19  | mΩ    |
|                                  |  | $V_{GS} = 10 \text{ V}, I_D = 9.0 \text{ A}, T_J = 125 ^{\circ}\text{C}$ |     | 17  | 21  |       |
| 9 <sub>FS</sub>                  | Forward Transconductance                                 | V <sub>DD</sub> = 5 V, I <sub>D</sub> = 9.0 A                            |     | 41  |     | S     |

### **Dynamic Characteristics**

| C <sub>iss</sub> | Input Capacitance            | V 45 V V 6 V   | 539 | 720 | pF |
|------------------|------------------------------|--|-----|-----|----|
| C <sub>oss</sub> | Output Capacitance           | $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$<br>f = 1  MHz | 172 | 230 | pF |
| C <sub>rss</sub> | Reverse Transfer Capacitance | 1 - 1 1011 12  | 24  | 35  | pF |
| $R_{\alpha}$     | Gate Resistance              |  | 1.3 |     | Ω  |

#### **Switching Characteristics**

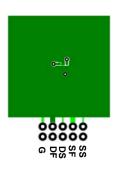
| t <sub>d(on)</sub>  | Turn-On Delay Time            |  | 6   | 12  | ns |
|---------------------|-------------------------------|--|-----|-----|----|
| t <sub>r</sub>      | Rise Time                     | $V_{DD} = 15 \text{ V}, I_D = 9.0 \text{ A},$                    | 2   | 10  | ns |
| t <sub>d(off)</sub> | Turn-Off Delay Time           | $V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$                      | 14  | 25  | ns |
| t <sub>f</sub>      | Fall Time                     |  | 2   | 10  | ns |
| 0                   | Total Gate Charge             | V <sub>GS</sub> = 0 V to 10 V                                    | 8.5 | 12  | nC |
| $Q_{g(TOT)}$        | Total Gate Charge             | $V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 15 \text{ V}$ | 4.1 | 5.8 | nC |
| $Q_{gs}$            | Total Gate Charge             | I <sub>D</sub> = 9.0 A   | 1.6 |     | nC |
| $Q_{gd}$            | Gate to Drain "Miller" Charge |  | 1.2 |     | nC |

#### **Drain-Source Diode Characteristics**

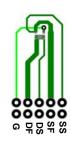
| $V_{SD}$        | Source to Drain Diode Forward Voltage | $V_{GS} = 0 \text{ V}, I_{S} = 2.0 \text{ A}$ (Note 2) | 0.75 | 1.2 | \/ |
|-----------------|---------------------------------------|--|------|-----|----|
|                 |                                       | $V_{GS} = 0 \text{ V}, I_{S} = 9.0 \text{ A}$ (Note 2) | 0.86 | 1.2 | V  |
| t <sub>rr</sub> | Reverse Recovery Time                 | -I <sub>E</sub> = 9.0 A, di/dt = 100 A/μs              | 16   | 28  | ns |
| Q <sub>rr</sub> | Reverse Recovery Charge               | 1F = 9.0 A, αι/αι = 100 A/μS                           | 4    | 10  | nC |

#### NOTES:

 $R_{0,C}$  is design while  $R_{0,C}$  is determined by the user's board design.



a. 52 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.



b. 145 °C/W when mounted on a minimum pad of 2 oz copper.

- 2. Pulse Test: Pulse Width < 300  $\mu\text{s},$  Duty cycle < 2.0 %.
- 3. As an N-ch device, the negative Vgs rating is for low duty cycle pulse occurrence only. No continuous rating is implied.

### Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

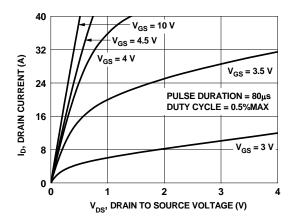


Figure 1. On Region Characteristics

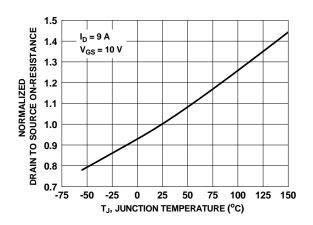


Figure 3. Normalized On Resistance vs Junction Temperature

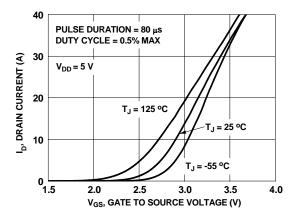


Figure 5. Transfer Characteristics

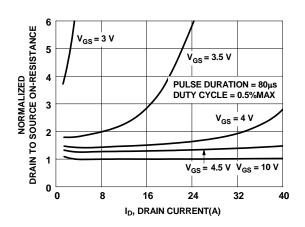


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

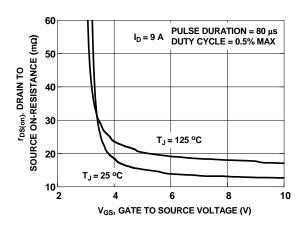


Figure 4. On-Resistance vs Gate to Source Voltage

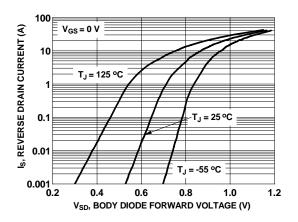


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

## Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

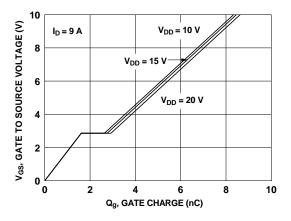


Figure 7. Gate Charge Characteristics

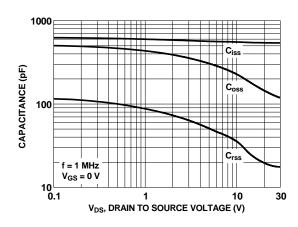


Figure 8. Capacitance vs Drain to Source Voltage

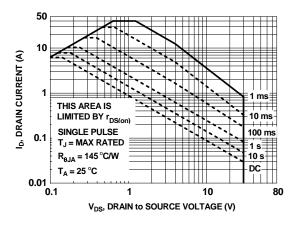


Figure 9. Forward Bias Safe Operating Area

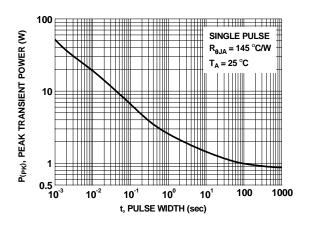


Figure 10. Single Pulse Maximum Power Dissipation

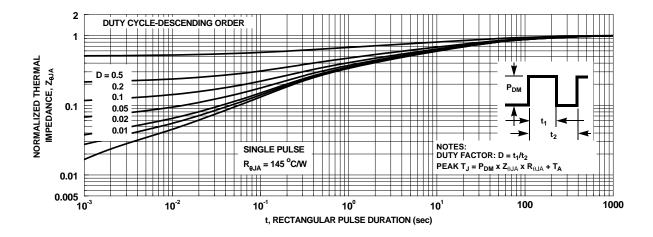
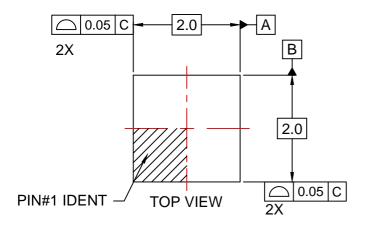
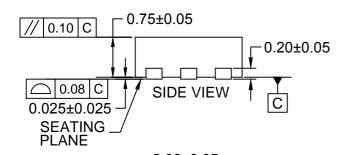
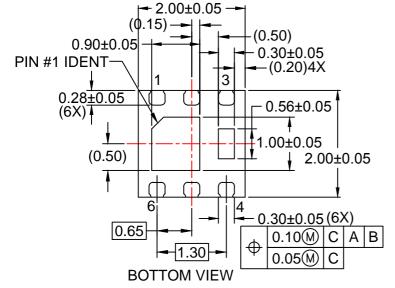


Figure 11. Junction-to-Ambient Transient Thermal Response Curve

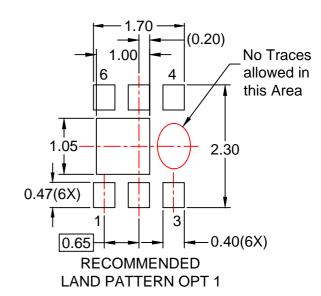


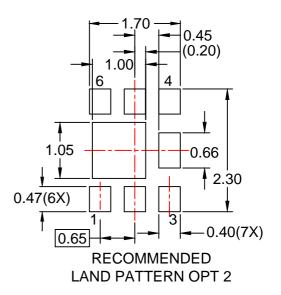




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